S1000-2M

PROPERTY	Typical Value	Units	Condition	Test Method
Glass Transition Temperature, Tg	185	°C	A	DMA IPC-TM-650 2.4.24.2
Glass Transition Temperature, Tg	180	°C	A	DSC IPC-TM650 2.4.25
Thermal Expansion, Z CTE	41	ppm/°C	A	Before Tg, IPC-TM-650 2.4.41
Thermal Expansion, Z CTE	208	ppm/°C	A	After Tg, IPC-TM-650 2.4.41
Decomposition Temperature, Td	355	°C	A	TMA IPC-TM650 2.4.24.6
Delamination Time, T260	60	minutes	A	TMA IPC-TM650 2.4.24
Delamination Time, T288	30	minutes	A	TMA IPC-TM650 2.4.24
Delamination Time, T300	15	minutes	A	TMA IPC-TM650 2.4.24
Dielectric Constant (Dk) - SPDR at 56% RC	4.49	-	1 GHz	IPC-TM-650 2.5.5.9
Dielectric Constant (Dk) - SPDR at 56% RC	4.9	-	1 MHz	IPC-TM-650 2.5.5.9
Dissipation Factor (Df) - SPDR at 56% RC	0.016	-	1 GHz	IPC-TM-650 2.5.5.9
Dissipation Factor (Df) - SPDR at 56% RC	0.015	-	1 MHz	IPC-TM-650 2.5.5.9
Volume Resistivity	8.66E+08	MΩ·cm	After moisture resistance	IPC-TM-650 2.5.17.1
Surface Resistivity	2.17E+07	MΩ	After moisture resistance	IPC-TM-650 2.5.17.1
Dielectric Breakdown	45+NB	kV	D-48/50+D-0.5/23	IPC-TM-650 2.5.6
Thermal Conductivity	0.7	W/m·K	100	ASTM D5470
Water Absorption	0.08	%	D-24/23	IPC-TM-650 2.6.2.1
Copper Peel Strength	1.3 (7.4)	N/mm (lb/in.)	after solder float 1 oz. EDC Foil	IPC-TM-650 2.4.8
Flammability	94V-0	-	A	UL